

- Members of the Texas Instruments *Widebus™* Family
- Inputs Are TTL-Voltage Compatible
- Provide Extra Data Width Necessary for Wider Address/Data Paths or Buses With Parity
- Flow-Through Architecture Optimizes PCB Layout
- Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise
- *EPIC™* (Enhanced-Performance Implanted CMOS) 1- μ m Process
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL) Packages Using 25-mil Center-to-Center Pin Spacings and 380-mil Fine-Pitch Ceramic Flat (WD) Packages Using 25-mil Center-to-Center Spacings

description

The 'ACT16825 18-bit buffers/drivers are designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters.

The 'ACT16825 can be used as two 9-bit buffers or one 18-bit buffer. They provide true data from A to Y.

The 3-state control gate is a 2-input NOR gate; therefore, if either output-enable ($\overline{OE1}$ or $\overline{OE2}$) input is high, all nine affected outputs are in the high-impedance state.

The 74ACT16825 is packaged in TI's shrink small-outline package, which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

The 54ACT16825 is characterized for operation over the full military temperature range of -55°C to 125°C . The 74ACT16825 is characterized for operation from -40°C to 85°C .

54ACT16825 . . . DW PACKAGE
74ACT16825 . . . DL PACKAGE
(TOP VIEW)

1	56	1	$\overline{OE2}$
1Y1	2	55	1A1
1Y2	3	54	1A2
GND	4	53	GND
1Y3	5	52	1A3
1Y4	6	51	1A4
V_{CC}	7	50	V_{CC}
1Y5	8	49	1A5
1Y6	9	48	1A6
1Y7	10	47	1A7
GND	11	46	GND
1Y8	12	45	1A8
1Y9	13	44	1A9
GND	14	43	GND
GND	15	42	GND
2Y1	16	41	2A1
2Y2	17	40	2A2
GND	18	39	GND
2Y3	19	38	2A3
2Y4	20	37	2A4
2Y5	21	36	2A5
V_{CC}	22	35	V_{CC}
2Y6	23	34	2A6
2Y7	24	33	2A7
GND	25	32	GND
2Y8	26	31	2A8
2Y9	27	30	2A9
2OE1	28	29	$\overline{OE2}$

FUNCTION TABLE
(each 9-bit section)

INPUTS			OUTPUT
$\overline{OE1}$	$\overline{OE2}$	A	Y
L	L	L	L
L	L	H	H
H	X	X	Z
X	H	X	Z

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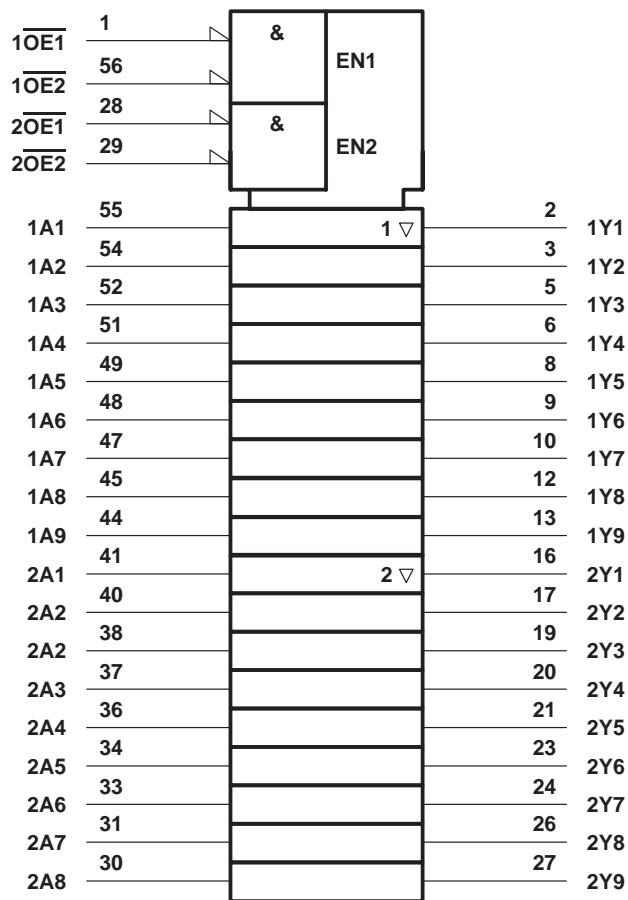


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54ACT16825, 74ACT16825
18-BIT BUFFERS/DRIVERS
WITH 3-STATE OUTPUTS

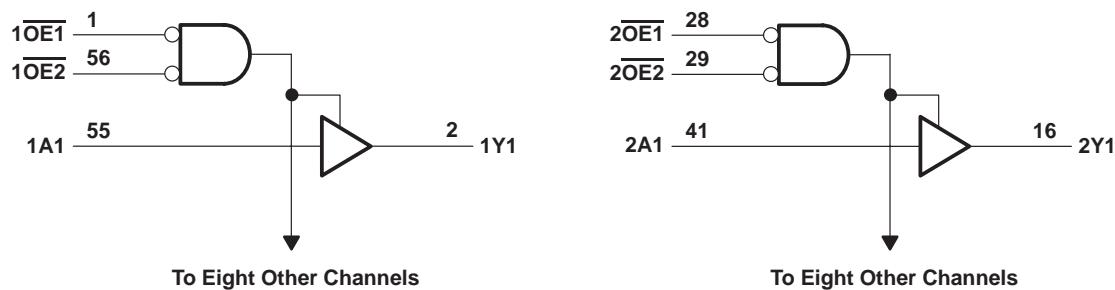
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logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC}	–0.5 V to 7 V		
Input voltage range, V_I (see Note 1)	–0.5 V to V_{CC} + 0.5 V		
Output voltage range, V_O (see Note 1)	–0.5 V to V_{CC} + 0.5 V		
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$)	±20 mA		
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$)	±50 mA		
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±50 mA		
Continuous current through V_{CC} or GND	±450 mA		
Maximum package power dissipation at $T_A = 55^\circ\text{C}$ (in still air) (see Note 2): DL package	1.4 W		
Storage temperature range, T_{stg}	–65°C to 150°C		

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.

recommended operating conditions (see Note 3)

		54ACT16825			74ACT16825			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.8			0.8	V
V_I	Input voltage	0	V_{CC}		0	V_{CC}		V
V_O	Output voltage	0	V_{CC}		0	V_{CC}		V
I_{OH}	High-level output current			–24			–24	mA
I_{OL}	Low-level output current			24			24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	0	10		0	10		ns/V
T_A	Operating free-air temperature	–55		125	–40		85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

**54ACT16825, 74ACT16825
18-BIT BUFFERS/DRIVERS
WITH 3-STATE OUTPUTS**

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	T _A = 25°C			54ACT16825	74ACT16825	UNIT
			MIN	TYP	MAX	MIN	MAX	
V _{OH}	I _{OH} = -50 µA	4.5 V	4.4			4.4	4.4	V
		5.5 V	5.4			5.4	5.4	
	I _{OH} = -24 mA	4.5 V	3.94			3.8	3.8	
		5.5 V	4.94			4.8	4.8	
	I _{OH} = -75 mA [†]	5.5 V				3.85	3.85	
V _{OL}	I _{OL} = 50 µA	4.5 V		0.1		0.1	0.1	V
		5.5 V		0.1		0.1	0.1	
	I _{OL} = 24 mA	4.5 V		0.36		0.44	0.44	
		5.5 V		0.36		0.44	0.44	
	I _{OL} = 75 mA [†]	5.5 V				1.65	1.65	
I _I	V _I = V _{CC} or GND	5.5 V		±0.1		±1	±1	µA
I _{OZ}	V _O = V _{CC} or GND	5.5 V		±0.5		±5	±5	µA
I _{CC}	V _I = V _{CC} or GND, I _O = 0	5.5 V			8	80	80	µA
ΔI _{CC} [‡]	One input at 3.4 V, Other inputs at V _{CC} or GND	5.5 V		0.9		1	1	mA
C _i	V _I = V _{CC} or GND	5 V		4				pF
C _o	V _O = V _{CC} or GND	5 V		16				pF

[†] Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

[‡] This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T _A = 25°C			54ACT16825	74ACT16825	UNIT
			MIN	TYP	MAX	MIN	MAX	
t _{PLH}	A	Y	4.1	7.5	9.3	4.1	10.5	4.1 10.5
t _{PHL}			3.1	7.5	9.6	3.1	10.3	3.1 10.3
t _{PZH}	OE	Y	3.3	7.9	9.9	3.3	11	3.3 11
t _{PZL}			4.1	9.5	12.1	4.1	13.2	4.1 13.2
t _{PHZ}	OE	Y	5.7	9	10.8	5.7	11.5	5.7 11.5
t _{PLZ}			5.5	8.5	10	5.5	10.6	5.5 10.6

operating characteristics, V_{CC} = 5 V, T_A = 25°C

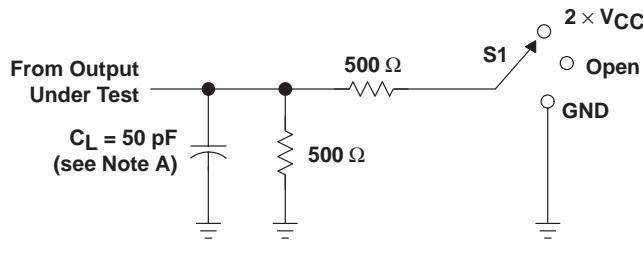
PARAMETER		TEST CONDITIONS		TYP	UNIT
C _{pd}	Power dissipation capacitance	Outputs enabled	C _L = 50 pF, f = 1 MHz	42	pF
				12	

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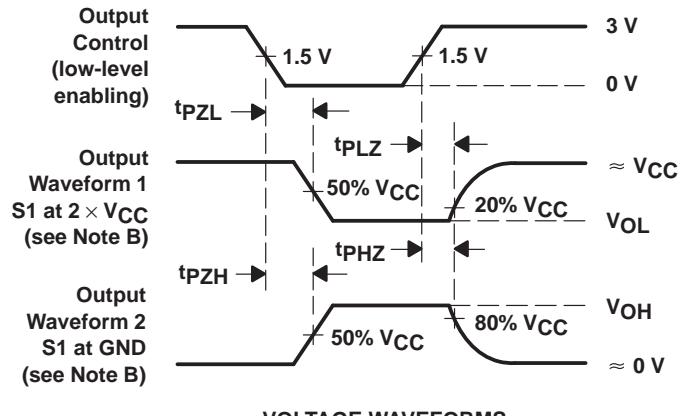
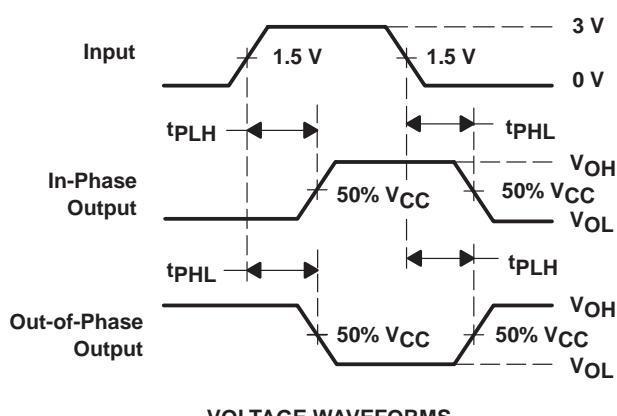


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PARAMETER MEASUREMENT INFORMATION



TEST	S1
t _{PLH} /t _{PHL}	Open
t _{PLZ} /t _{PZL}	2 \times V _{CC}
t _{PHZ} /t _{PZH}	GND



- NOTES:
- C_L includes probe and jig capacitance.
 - Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, $Z_O = 50 \Omega$, $t_r = 3$ ns, $t_f = 3$ ns.
 - The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
74ACT16825DL	Obsolete	Production	SSOP (DL) 56	-	-	Call TI	Call TI	-40 to 85	ACT16825
74ACT16825DLR	Active	Production	SSOP (DL) 56	1000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ACT16825
74ACT16825DLR.A	Active	Production	SSOP (DL) 56	1000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ACT16825

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

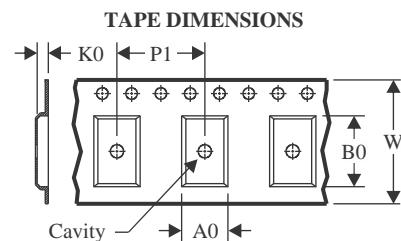
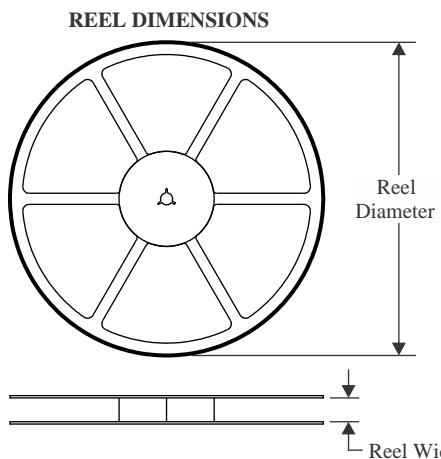
⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

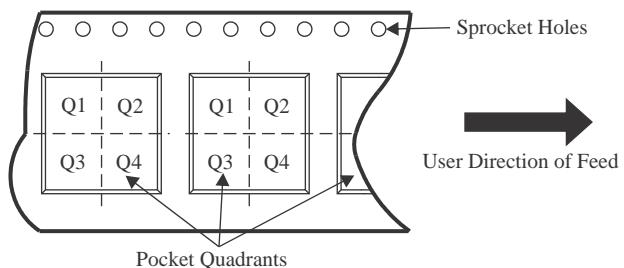
Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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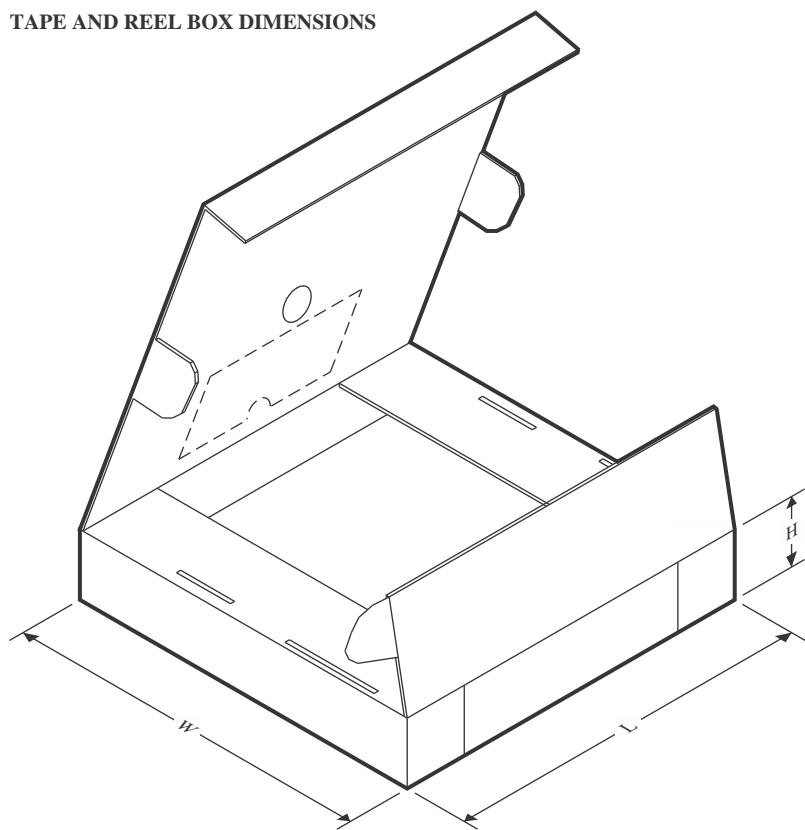
TAPE AND REEL INFORMATION


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
74ACT16825DLR	SSOP	DL	56	1000	330.0	32.4	11.35	18.67	3.1	16.0	32.0	Q1

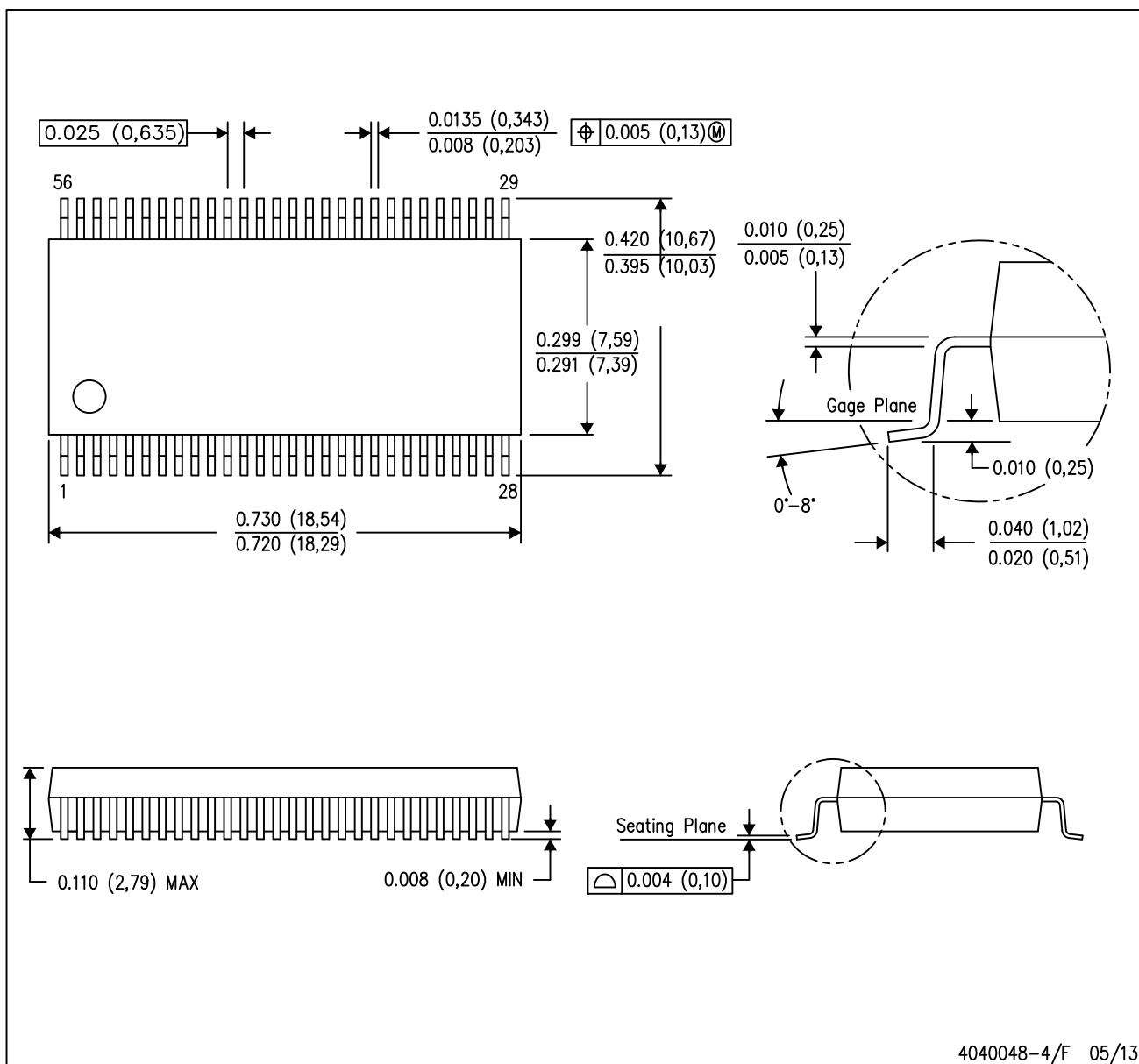
TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
74ACT16825DLR	SSOP	DL	56	1000	356.0	356.0	53.0

DL (R-PDSO-G56)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0.15).
 - Falls within JEDEC MO-118

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